## **GP1S25**

#### ■ Features

1. Side lead ultra-compact transmission type

2. Conforming to solder reflow

Pre-heat: 160 °C, MAX. 120 sec Reflow: (200 °C, MAX. 60 sec) 240 °C, MAX. 10 sec)

3. Slit : 0.3 mm 4. Gap : 1.6 mm

## ■ Applications

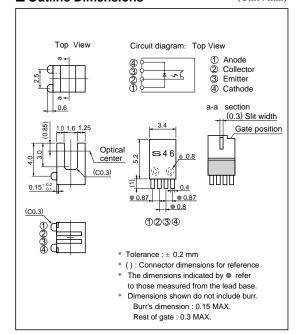
1. CD-ROM drives

2. FDDs

# Side Lead Type Ultra-compact Photointerrupter

#### **■** Outline Dimensions

(Unit: mm)



## ■ Absolute Maximum Ratings

 $(Ta=25^{\circ}C)$ 

	Parameter	Symbol	Rating	Unit	
Input	Forward current	$I_{\mathrm{F}}$	50	mA	
	Reverse voltage	V <sub>R</sub>	6	V	
	Power dissipation	P	75	mW	
Output	Collector-emitter voltage	V <sub>CEO</sub>	35	V	
	Emitter-collector voltage	$V_{ECO}$	6	V	
	Collector current	$I_{\rm C}$	20	mA	
	Collector power dissipation	Pc	75	mW	
Total power dissipation		P <sub>tot</sub>	100	mW	
Operating temperature		T opr	- 25 to + 85	°C	
Storage temperature		T stg	- 40 to + 100	°C	
*1 Soldering temperature		T sol	260	°C	

<sup>\*1</sup> Soldering time: For 3 seconds (hand soldering)



### **■** Electro-optical Characteristics

(Ta=25 °C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Lamust	Forward voltage		V <sub>F</sub>	$I_F=20mA$	-	1.2	1.4	V
Input	Reverse current		$I_R$	$V_R = 3V$	-	-	10	μΑ
Output	Dark current		I <sub>CEO</sub>	$V_{CE} = 20V$	-	-	100	nA
	Collector current		$I_{\rm C}$	$V_{CE}=5V,I_F=5mA$	50	-	300	μΑ
Transfer	Collector-emitter saturation voltage		V CE(sat)	$I_F=10mA,I_C=50\mu\;A$	-	-	0.4	V
characteristics	Response time	Rise time	t <sub>r</sub>	$V_{CE}=5V,~I_{C}=100\mu$ A	-	35	100	μs
		Fall time	$t_{\mathrm{f}}$	$R_L=1~000~\Omega$	-	35	100	μs

Fig. 1 Forward Current vs. Ambient Temperature

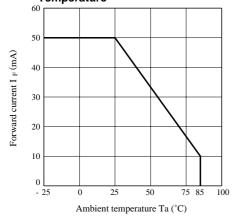


Fig. 3 Forward Current vs. Forward Voltage

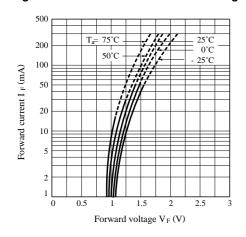


Fig. 2 Power dissipation vs. Ambient Temperature

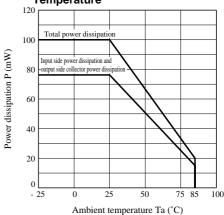


Fig. 4 Collector Current vs. Forward Current

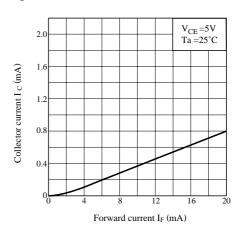


Fig. 5 Collector Current vs. Collector-emitter Voltage

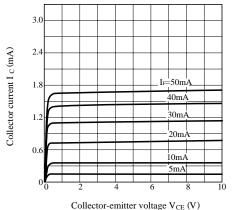


Fig. 7 Collector-emitter Saturation Voltage vs. Ambient Temperature

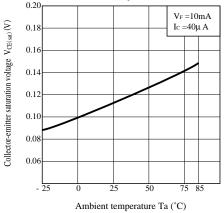


Fig. 9 Response Time vs. Load Resistance

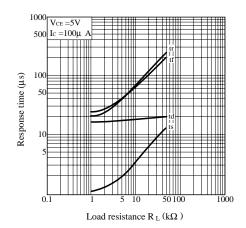


Fig. 6 Relative Collector Current vs.
Ambient Temperature

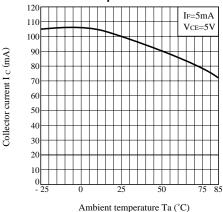
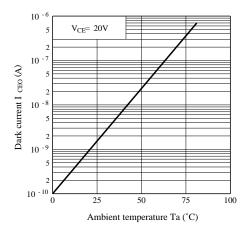
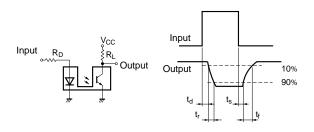


Fig. 8 Dark Current vs. Ambient Temperature

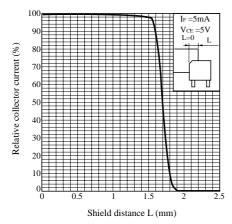


**Test Circuit for Response Time** 



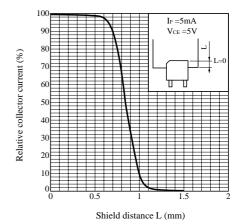


## Fig. 10 Detecting Position Characteristics (1)



 $\bullet\,$  Please refer to the chapter "Precautions for Use".

Fig. 11 Detecting Position Characteristics (2)



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